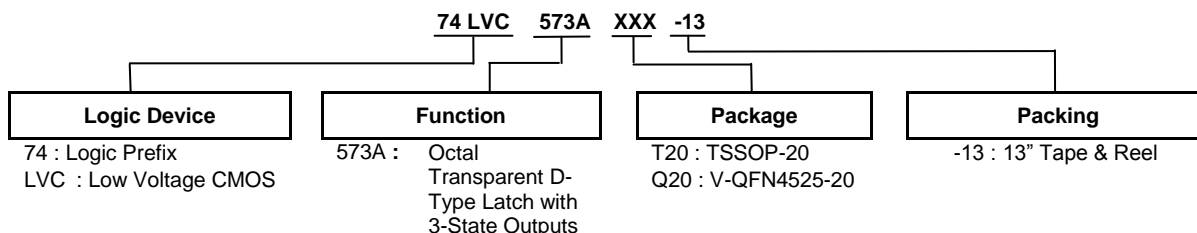


## Ordering Information



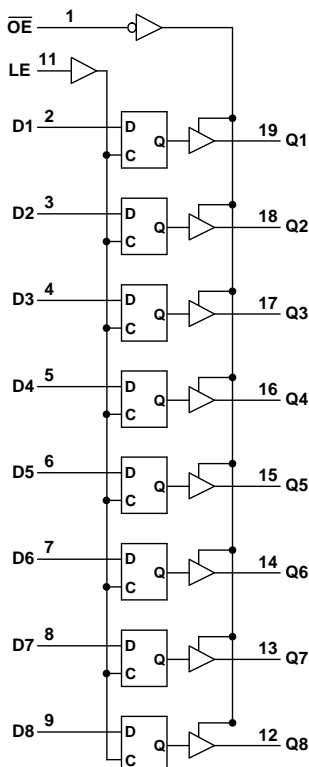
Part Number	Package Code	Package (Notes 4 & 5)	Package Size	13" Tape and Reel	
				Quantity	Part Number Suffix
74LVC573AT20-13	T20	TSSOP-20	6.4mm X 6.5mm X 1.2mm 0.65mm Lead Pitch	2500/Tape & Reel	-13
74LVC573AQ20-13	Q20	V-QFN4525-20	2.5mm X 4.5mm X 0.95mm 0.50mm Lead Pitch	2500/Tape & Reel	-13

Notes: 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.  
5. V-QFN4525-20 is a JEDEC recognized naming convention that specifies the package thickness category as V and the number 4525 describes the package as 4.5mm X 2.5mm.

## Pin Descriptions

Pin Number	Pin Name	Description
1	$\overline{OE}$	Output Enable
2	D1	Data Input
3	D2	Data Input
4	D3	Data Input
5	D4	Data Input
6	D5	Data Input
7	D6	Data Input
8	D7	Data Input
9	D8	Data Input
10	GND	Ground
11	LE	Latch Enable
12	Q8	Latch Output
13	Q7	Latch Output
14	Q6	Latch Output
15	Q5	Latch Output
16	Q4	Latch Output
17	Q3	Latch Output
18	Q2	Latch Output
19	Q1	Latch Output
20	V <sub>CC</sub>	Supply Voltage

## Logic Diagram



## Function Table

(Each Latch)			
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q <sub>0</sub>
H	X	X	Z

## Absolute Maximum Ratings (Notes 6 & 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to +7.0	V
V <sub>I</sub>	Input Voltage Range	-0.5 to +7.0	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0V	-20	mA
I <sub>OK</sub>	Output Clamp Current V <sub>O</sub> < 0V	-50	mA
I <sub>O</sub>	Continuous Output Current -0.5V < V <sub>O</sub> < V <sub>CC</sub> +0.5V	±50	mA
I <sub>CC</sub>	Continuous Current Through V <sub>CC</sub>	100	mA
I <sub>GND</sub>	Continuous Current Through GND	-100	mA
T <sub>J</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>TOT</sub>	Total Power Dissipation	500	mW

- Notes:
- Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
  - Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

## Recommended Operating Conditions (Note 8)

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	Operating	1.65	3.6	V
		Data Retention Only	1.5	—	V
V <sub>I</sub>	Input Voltage	—	0	5.5	V
V <sub>O</sub>	Output Voltage	—	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-Level Output Current	V <sub>CC</sub> = 1.65V	—	-4	mA
		V <sub>CC</sub> = 2.3V	—	-8	
		V <sub>CC</sub> = 2.7V	—	-12	
		V <sub>CC</sub> = 3.0V	—	-24	
I <sub>OL</sub>	Low-Level Output Current	V <sub>CC</sub> = 1.65V	—	4	mA
		V <sub>CC</sub> = 2.3V	—	8	
		V <sub>CC</sub> = 2.7V	—	12	
		V <sub>CC</sub> = 3.0V	—	24	
Δt/ΔV	Input Transition Rise or Fall Rate	—	—	10	ns/V
T <sub>A</sub>	Operating Free-Air Temperature	—	-40	+125	°C

- Note: 8. Unused inputs should be held at V<sub>CC</sub> or Ground.

**Electrical Characteristics**

Symbol	Parameter	Test Conditions		V <sub>CC</sub>	T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -40°C to +125°C		Unit
					Min	Max	Min	Max	
V <sub>IH</sub>	High-Level Input Voltage	—		1.65V to 1.95V	V <sub>CC</sub> X 0.65	—	V <sub>CC</sub> X 0.65	—	V
		—		2.3V to 2.7V	1.7	—	1.7	—	
		—		3.0V to 3.6V	2	—	2	—	
V <sub>IL</sub>	Low-Level Input Voltage	—		1.65V to 1.95V	—	V <sub>CC</sub> X 0.35	—	V <sub>CC</sub> X 0.35	V
		—		2.3V to 2.7V	—	0.7	—	0.7	
		—		3.0V to 3.6V	—	0.8	—	0.8	
V <sub>OH</sub>	High-Level Output Voltage	I <sub>OH</sub> = -50μA		1.65V to 3.6V	V <sub>CC</sub> -0.2	—	V <sub>CC</sub> -0.3	—	V
		I <sub>OH</sub> = -4mA		1.65V	1.2	—	1.05	—	
		I <sub>OH</sub> = -8mA		2.3V	1.7	—	1.65	—	
		I <sub>OH</sub> = -12mA		2.7V	2.2	—	2.05	—	
				3.0V	2.4	—	2.48	—	
		I <sub>OH</sub> = -24mA		3.0V	2.3	—	2.0	—	
V <sub>OL</sub>	Low-Level Output Voltage	I <sub>OL</sub> = 100μA		1.65V to 3.6V	—	0.2	—	0.3	V
		I <sub>OL</sub> = 4mA		1.65V	—	0.45	—	0.65	
		I <sub>OL</sub> = 8mA		2.3V	—	0.60	—	0.80	
		I <sub>OL</sub> = 12mA		2.7V	—	0.40	—	0.60	
		I <sub>OL</sub> = 24mA		3.0V	—	0.55	—	0.80	
I <sub>OFF</sub>	Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 0 or 5.5V		0V	—	±10	—	20	μA
I <sub>I</sub>	Input Current Control Pins	V <sub>I</sub> = GND or 5.5V		0 to 3.6V	—	±5	—	±20	μA
I <sub>OZ</sub>	Z-State Current Including Input Current I/O Pins	V <sub>I</sub> = GND or 5.5V V <sub>O</sub> = 0 to 5.5V		3.6V	—	±5	—	±20	μA
I <sub>CC</sub>	Supply Current	V <sub>I</sub> = GND or V <sub>CC</sub> , I <sub>O</sub> = 0		3.6V	—	10	—	40	μA
ΔI <sub>CC</sub>	Additional Supply Current	One Input at V <sub>CC</sub> -0.6V I <sub>O</sub> = 0A		2.7V to 3.6V	—	500	—	5000	μA
C <sub>I</sub>	Input Capacitance	Control Pins	V <sub>I</sub> = GND or V <sub>CC</sub>	0V to 3.6V	4.0 Typical		4.0 Typical		pF
		I/O Pins			5.5 Typical		5.5 Typical		

## Switching Characteristics

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t <sub>W</sub>	Pulse Width LE	Figure 1	1.8V ± 0.15V	5.0	2.5	—	5.0	—	5.5	—	ns
			2.5V ± 0.2V	4.0	2.0	—	4.0	—	4.5	—	
			2.7V	3.0	1.7	—	3.0	—	3.5	—	
			3.3V ± 0.3V	3.0	1.5	—	3.0	—	3.5	—	
t <sub>SU</sub>	Set-up Time D <sub>N</sub> to LE	Figure 1	1.8V ± 0.15V	4.0	2.0	—	4.0	—	4.5	—	ns
			2.5V ± 0.2V	3.0	1.5	—	3.0	—	3.5	—	
			2.7V	2.0	1.0	—	2.0	—	2.5	—	
			3.3V ± 0.3V	2.0	1.0	—	2.0	—	2.5	—	
t <sub>H</sub>	Hold Time D <sub>N</sub> to LE	Figure 1	1.8V ± 0.15V	3.0	1.5	—	3.0	—	3.5	—	ns
			2.5V ± 0.2V	2.0	1.0	—	2.0	—	2.5	—	
			2.7V	1.5	1.0	—	1.5	—	2.0	—	
			3.3V ± 0.3V	1.5	1.0	—	1.5	—	2.0	—	
t <sub>PD</sub>	Propagation Delay D <sub>N</sub> to Q <sub>N</sub>	Figure 1	1.8V ± 0.15V	1	6	12.2	1	12.7	1	16.9	ns
			2.5V ± 0.2V	1	3.9	7.8	1	8.3	1	8.7	
			2.7V	1	4.2	7.8	1	8.1	1	9.5	
			3.3V ± 0.3V	1.5	3.8	6.8	1.5	7.4	1.5	8	
t <sub>PD</sub>	Propagation Delay LE to Q <sub>N</sub>	Figure 1	1.8V ± 0.15V	1	7	14.8	1	15.3	1	22.5	ns
			2.5V ± 0.2V	1	4.5	10	1	10.5	1	12.4	
			2.7V	1	5.4	8.2	1	9.5	1	12	
			3.3V ± 0.3V	1.5	4.4	7.2	1.5	8.5	1.5	11	
t <sub>EN</sub>	Enable Time to Q <sub>N</sub> $\overline{\text{OE}}$	Figure 1	1.8V ± 0.15V	1	7.8	16.5	1	17	1	18.7	ns
			2.5V ± 0.2V	1	4	9	1	9.5	1	10.3	
			2.7V	1	4.4	8.3	1	8.5	1	9.5	
			3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9	
t <sub>DIS</sub>	Disable Time to Q <sub>N</sub> $\overline{\text{OE}}$	Figure 1	1.8V ± 0.15V	1	7.8	16.5	1	17	1	18.4	ns
			2.5V ± 0.2V	1	4	9	1	9.5	1	10.5	
			2.7V	1	4.4	8.3	1	8.5	1	9.1	
			3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9	
t <sub>DIS</sub>	Disable Time to Q <sub>N</sub> $\overline{\text{OE}}$	Figure 1	1.8V ± 0.15V	1	7.8	16.5	1	17	1	18.4	ns
			2.5V ± 0.2V	1	4	9	1	9.5	1	10.5	
			2.7V	1	4.4	8.3	1	8.5	1	9.1	
			3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9	
tsk(0)	Output Skew Time	—	3.3V ± 0.3V	—	—	1.0	—	—	—	1.5	ns

## Operating Characteristics

 T<sub>A</sub> = +25°C

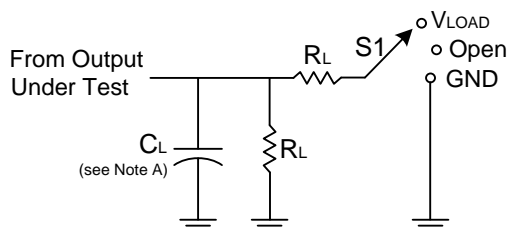
Symbol	Parameter	Test Conditions	V <sub>CC</sub>	Typ	Unit
C <sub>PD</sub>	Power Dissipation Capacitance per Gate	f = 10MHz Outputs Enabled	1.8V ± 0.15V	9.9	pF
			2.5V ± 0.2V	10.2	
			3.3V ± 0.3V	10.6	

## Package Characteristics

Symbol	Parameter	Package	Test Conditions	Min	Typ	Max	Unit
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	TSSOP-20	(Note 9)	—	74	—	°C/W
$\theta_{JC}$	Thermal Resistance Junction-to-Case	TSSOP-20	(Note 9)	—	15	—	°C/W
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	V-QFN4525-20	(Note 9)	—	67	—	°C/W
$\theta_{JC}$	Thermal Resistance Junction-to-Case	V-QFN4525-20	(Note 9)	—	20	—	°C/W

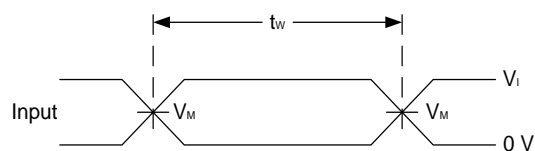
Note: 9. Test conditions for TSSOP-20 and V-QFN4525-20: Devices mounted on 4 layer FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout per JESD 51-7.

## Parameter Measurement Information

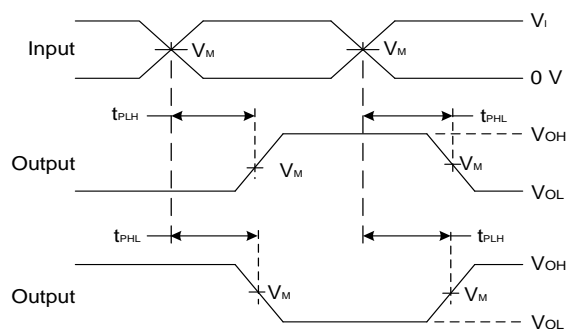


TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

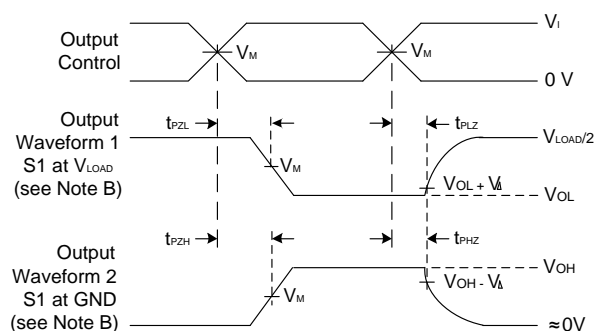
$V_{CC}$	Inputs		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8V \pm 0.15V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	1K $\Omega$	0.15V
$2.5V \pm 0.2V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	500 $\Omega$	0.15V
2.7V	2.7V	$\leq 2.5ns$	1.5V	6V	50pF	500 $\Omega$	0.3V
$3.3V \pm 0.3V$	2.7V	$\leq 2.5ns$	1.5V	6V	50pF	500 $\Omega$	0.3V



Voltage Waveform Pulse Duration



Voltage Waveform Propagation Delay Times  
Inverting and Non Inverting Outputs



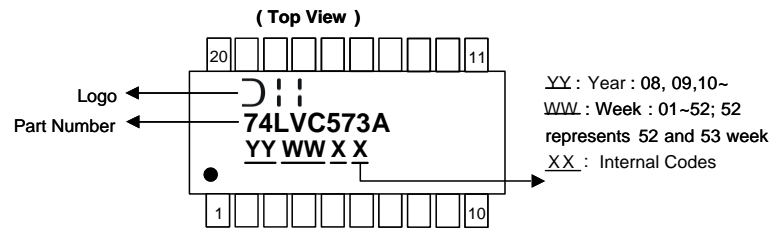
Voltage Waveform Enable and Disable Times  
Low and High Level Enabling

- Notes:
- A. Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate  $\leq 10MHz$ .
  - C. Inputs are measured separately one transition per measurement.
  - D.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{DIS}$ .
  - E.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{ENO}$ .
  - F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

Figure 1 Load Circuit and Voltage Waveforms

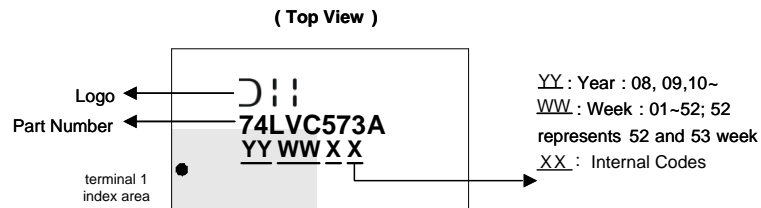
## Marking Information

### (1) TSSOP-20



Part Number	Package
74LVC573AT20	TSSOP-20

### (2) V-QFN4525-20

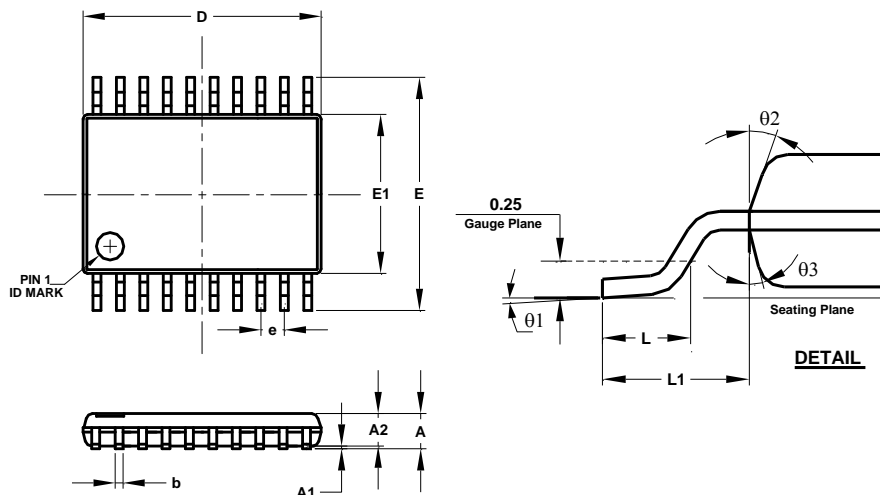


Part Number	Package
74LVC573AQ20	V-QFN4525-20

# Package Outline Dimensions

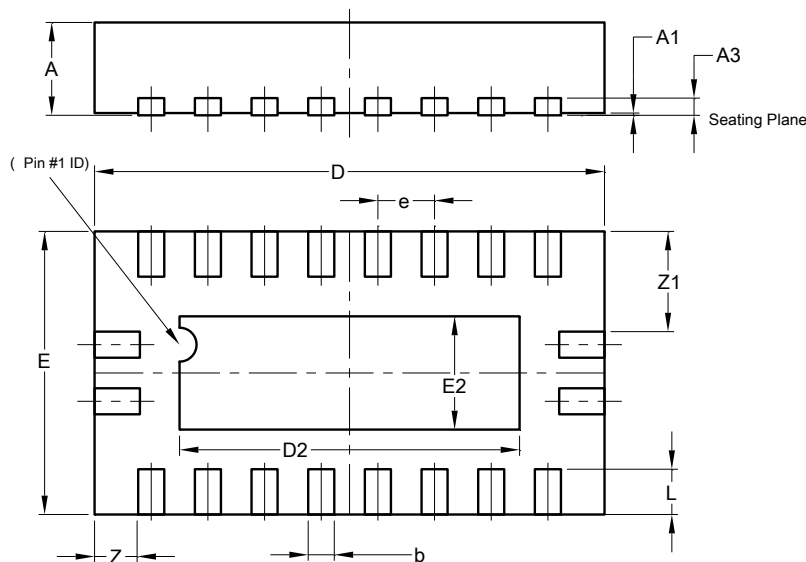
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

## (1) Package Type: TSSOP-20



TSSOP-20			
Dim	Min	Max	Typ
A	-	1.20	-
A1	0.05	0.15	-
A2	0.80	1.05	-
b	0.19	0.30	-
c	0.09	0.20	-
D	6.40	6.60	6.50
E	6.20	6.60	6.40
E1	4.30	4.50	4.40
e	0.65 BSC		
L	0.45	0.75	0.60
L1	1.0 REF		
θ1	0°	8°	-
θ2	10°	14°	12°
θ3	10°	14°	12°
All Dimensions in mm			

## (2) Package Type: V-QFN4525-20

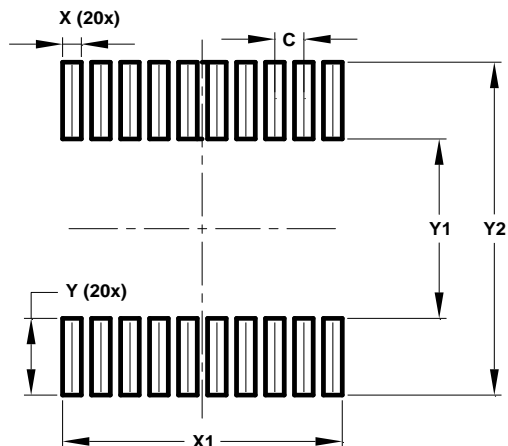


V-QFN4525-20			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	-	-	0.15
b	0.18	0.30	0.23
D	4.45	4.55	4.50
D2	2.85	3.15	3.00
E	2.45	2.55	2.50
E2	0.85	1.15	1.00
e	0.50BSC		
L	0.30	0.50	0.40
Z	-	-	0.385
Z1	-	-	0.885
All Dimensions in mm			

## Suggested Pad Layout

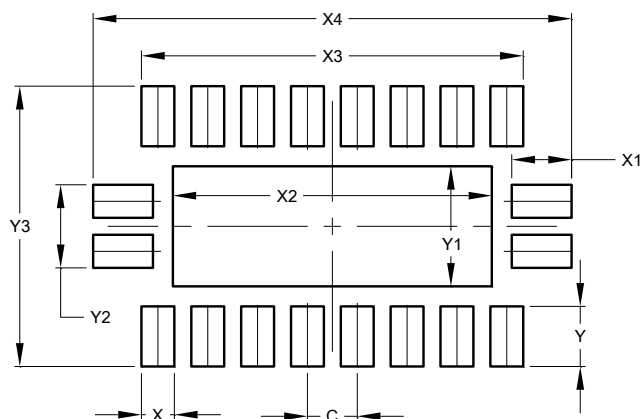
Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.

### (1) Package Type: TSSOP-20



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	6.270
Y	1.780
Y1	4.160
Y2	7.720

### (2) Package Type: V-QFN4525-20



Dimensions	Value (in mm)
C	0.500
X	0.330
X1	0.600
X2	3.200
X3	3.830
X4	4.800
Y	0.600
Y1	1.200
Y2	0.830
Y3	2.800

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